

### **REMARKS**

Claims 1, 2 and 5-11 are pending in the above application. By the above amendment, claims 3 and 4 have been cancelled, and claims 7-11 have been added.

The Office Action dated December 15, 2005, has been received and carefully reviewed. Each issue raised in that Office Action is addressed below.

### **CLAIM OBJECTION**

Claim 2 was objected to for reciting a lead "thickness" instead of a "width." It is respectfully submitted that "width" is the term that is intended. Figure 1, for example, illustrates leads 12 and 13 so that their length and width dimensions are visible. The thickness of these leads extends in a direction normal to the page. Paragraph 0067, for example, describes the squeezing of certain leads by a mold which would reduce the thickness of the leads, not their widths. For the foregoing reasons, the objection to claim 2 is respectfully traversed.

### **CLAIM REJECTIONS UNDER 35 U.S.C. 112, SECOND PARAGRAPH**

Claim 2 is rejected under 35 U.S.C. 112, second paragraph on the basis that there is no frame of reference for having the thickness of the leads "reduced." It is respectfully submitted that the leads inherently have an initial thickness which does not need to be positively recited in the claims. See, for example, MPEP 2173.05(e) (Inherent components of elements recited have antecedent basis in the recitation of the components themselves. For example, the limitation "the outer surface of said sphere" would not require an antecedent recitation that the sphere has an outer surface).

The Office Action also states that "it is not known if this thickness is reduced from another portion of the second lead or if this is in reference to an attribute that is changed prior to completing the final structure." The issue raised by this statement is not clear. However, it is

believed that the fact that 1) the claim is directed to the thickness and not the width of the lead and 2) the fact that the leads have an initial thickness and that this initial thickness is reduced make this claim definite and in compliance with 35 U.S.C. 112, second paragraph. The rejection based on 35 U.S.C. 112, second paragraph, is therefore respectfully traversed.

CLAIM REJECTIONS UNDER 35 U.S.C. 102(b)

Claim 1 is rejected under 35 U.S.C. 102(b) as being anticipated by Yasuda. The Yasuda application was filed January 13, 2003. The priority date of the present application is November 18, 2002. A verified English translation of the priority document is submitted herewith to perfect Applicant's priority claim. In view of this submission, it is respectfully submitted that Yasuda no longer qualifies as prior art, and the withdrawal of this rejection and the allowance of claim 1 is respectfully requested.

Claims 2, 5 and 6 depend from claim 1 and are submitted to be allowable for the same reasons as claim 1.

New claim 7 is also submitted to be allowable over the art of record. Claim 7 requires a method of manufacturing a semiconductor device using a leadframe that includes steps of providing a leadframe having at least two parallel first leads spaced by a first pitch and at least two parallel second leads spaced by a second pitch different than said first pitch and joined end-to-end with the first leads, mounting a semiconductor element on the leadframe, encapsulating the semiconductor in a package, and separating the second leads from said first leads. This method is not shown or suggested by the art of record, and claim 7 is therefore submitted to be allowable.

New claim 8 defines a method for manufacturing first and second different semiconductor devices from first and second identical leadframes. The method involves providing first and second leadframes that each have at least two parallel first leads spaced by a first pitch and at least two parallel second leads spaced by a second pitch different than said first pitch and joined end-to-end with the first leads. A first semiconductor element is mounted on the

first leadframe, and a second semiconductor element is mounted on the second leadframe, and the first semiconductor is encapsulated in a first package, and the second semiconductor is encapsulated in a second package different than the first package. The at least two parallel second leads of the first leadframe are bent at an angle to the at least two parallel first leads of the first leadframe, and the at least two parallel second leads of the second leadframe are separated from the at least two parallel first leads of the second leadframe. This method is not shown or suggested by the art of record, and claim 8 is therefore submitted to be allowable. Claims 9-11 depend from claim 8 and are submitted to be allowable for at least the same reasons as claim 8.

#### CONCLUSION

Each issue raised in the Office Action dated December 15, 2005, has been addressed, and it is believed that claims 1, 2 and 5-11 are in condition for allowance. Wherefore, reconsideration and allowance of these claims is earnestly solicited.

Should there be any outstanding matters that need to be resolved in the present application, the Examiner is respectfully requested to contact Scott Wakeman (Reg. No. 37,750) at the telephone number of the undersigned below, to conduct an interview in an effort to expedite prosecution in connection with the present application.

Application No. 10/690,615  
Amendment dated March 9, 2006  
Reply to Office Action of December 15, 2005

Docket No.: 0951-0127P

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2448 for any additional fees required under 37 C.F.R. §§ 1.16 or 1.17; particularly, extension of time fees.

Dated:

Respectfully submitted,

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